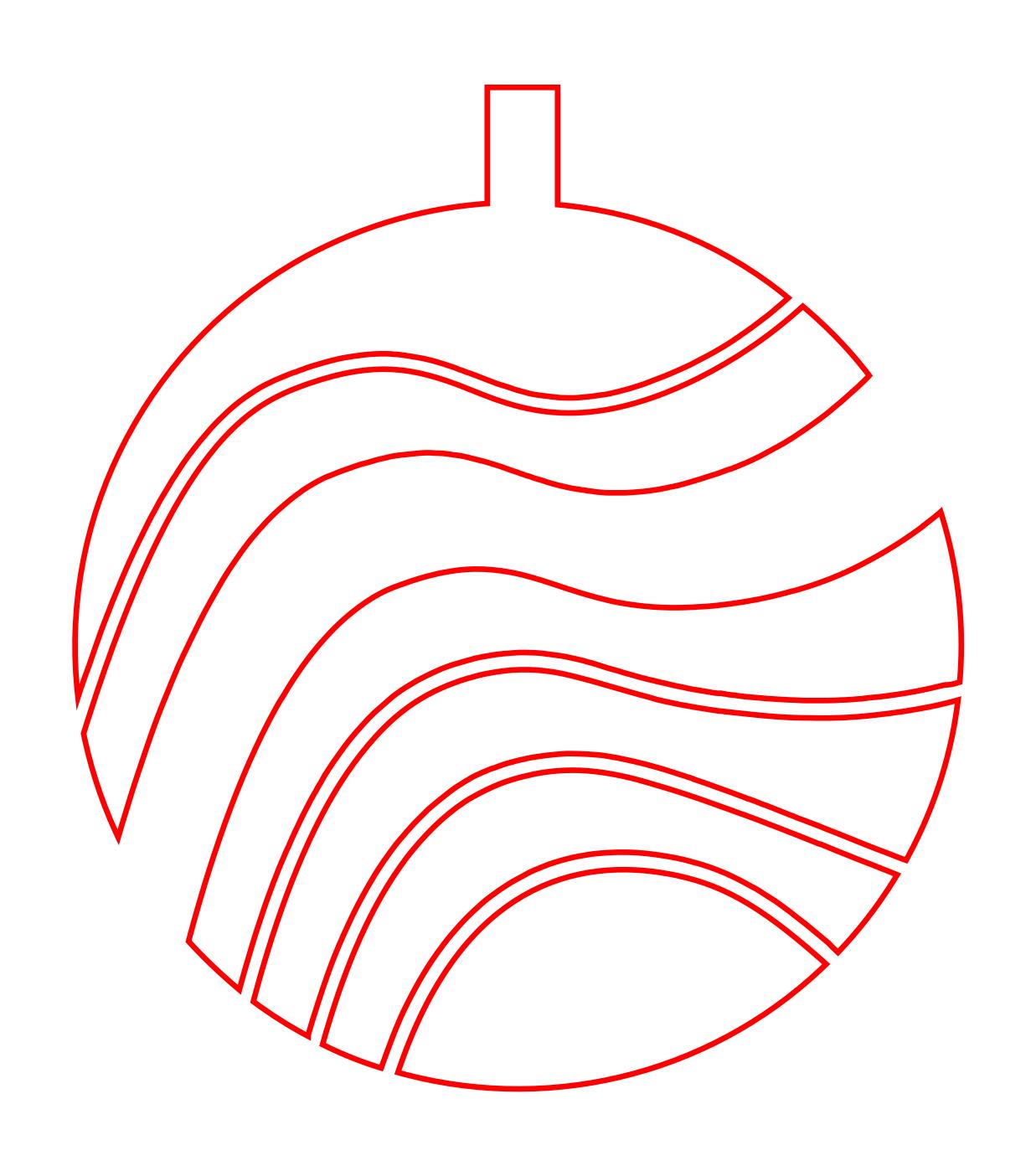
CUTTING PASS # 1

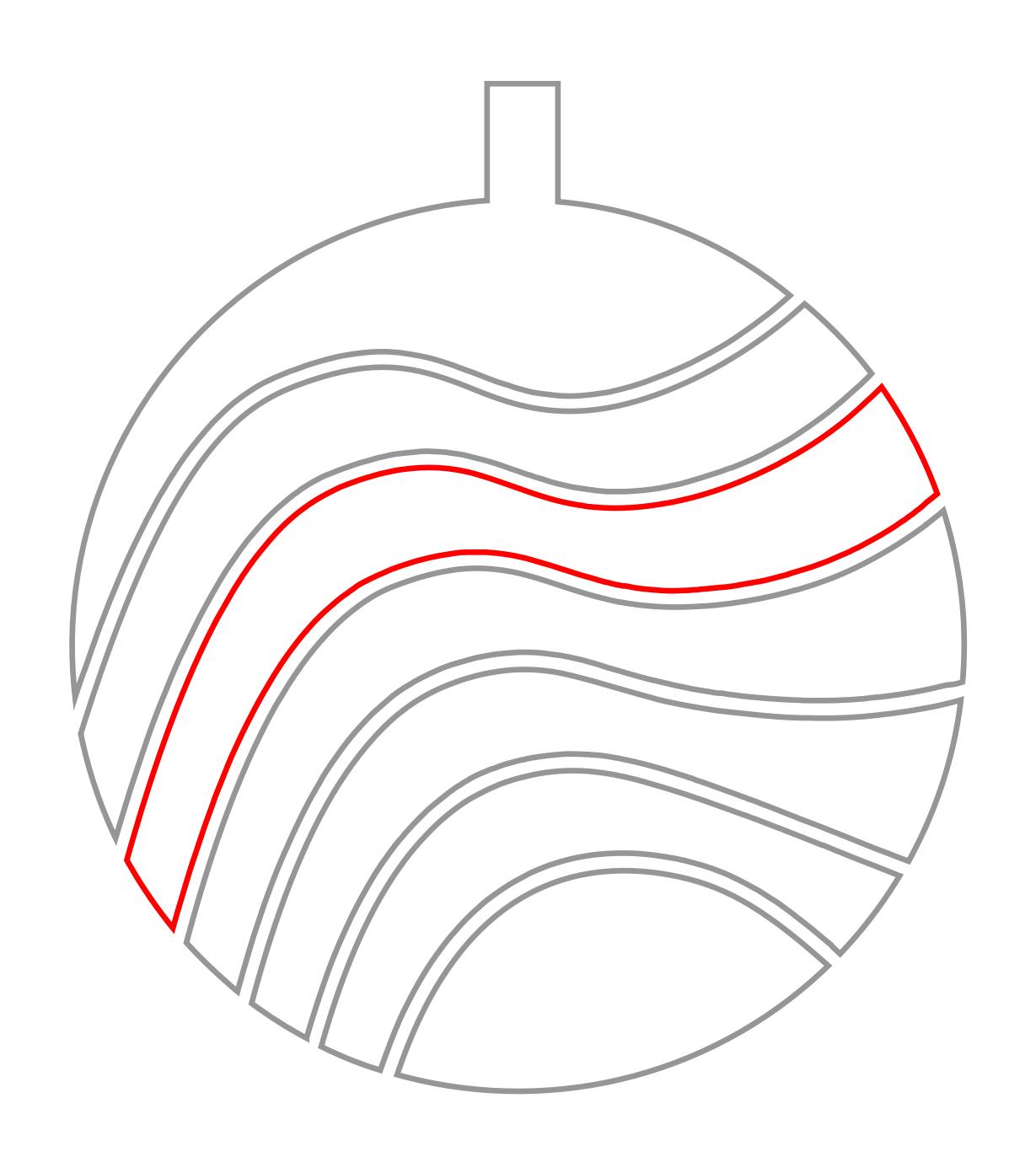
PLACE BASE AREA MINITER PLACE A SHEET OF 0.023MM CELLOPHANE IN THE LASER CUTTER



POWER: 12.5% SPEED: 3%

LASER Z: 0.023 MM

CUTTING PASS # 2 PLACE-BASESMENTER PLACE A SHEET OF 0.035MM CELLOPHANE IN THE LASER CUTTER



POWER: 12.5% SPEED: 3% LASER Z: 0.035 MM

CUTTING PASS # 3

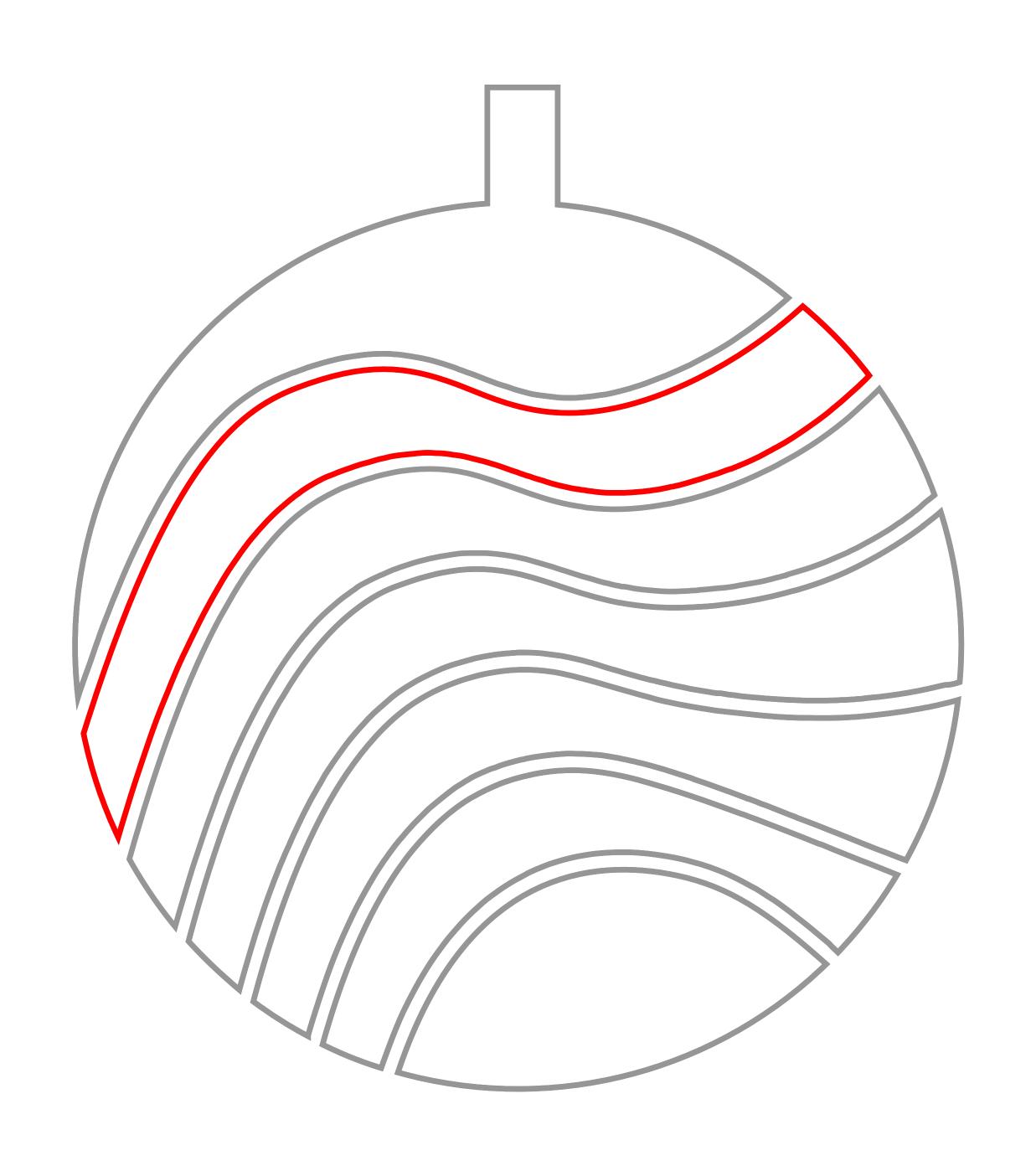
PLACE BASE AREA MINITURE PLACE BASER CUTTER

PLACE A SHEET OF 0.023MM CELLOPHANE IN THE LASER CUTTER



POWER: 12.5% SPEED: 3%

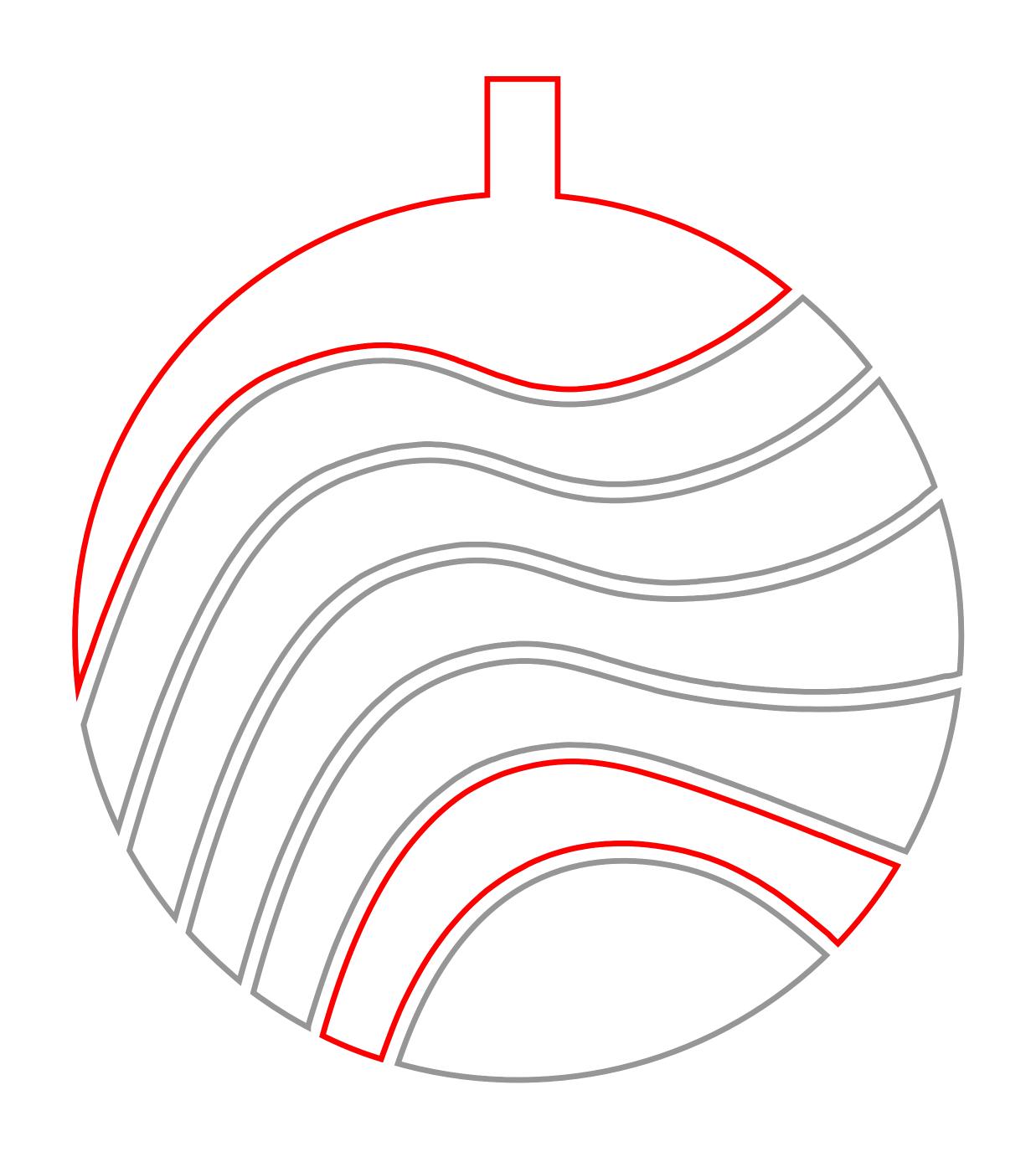
LASER Z: 0.046 MM



POWER: 12.5% SPEED: 3% LASER Z: 0.058 MM

CUTTING PASS # 5

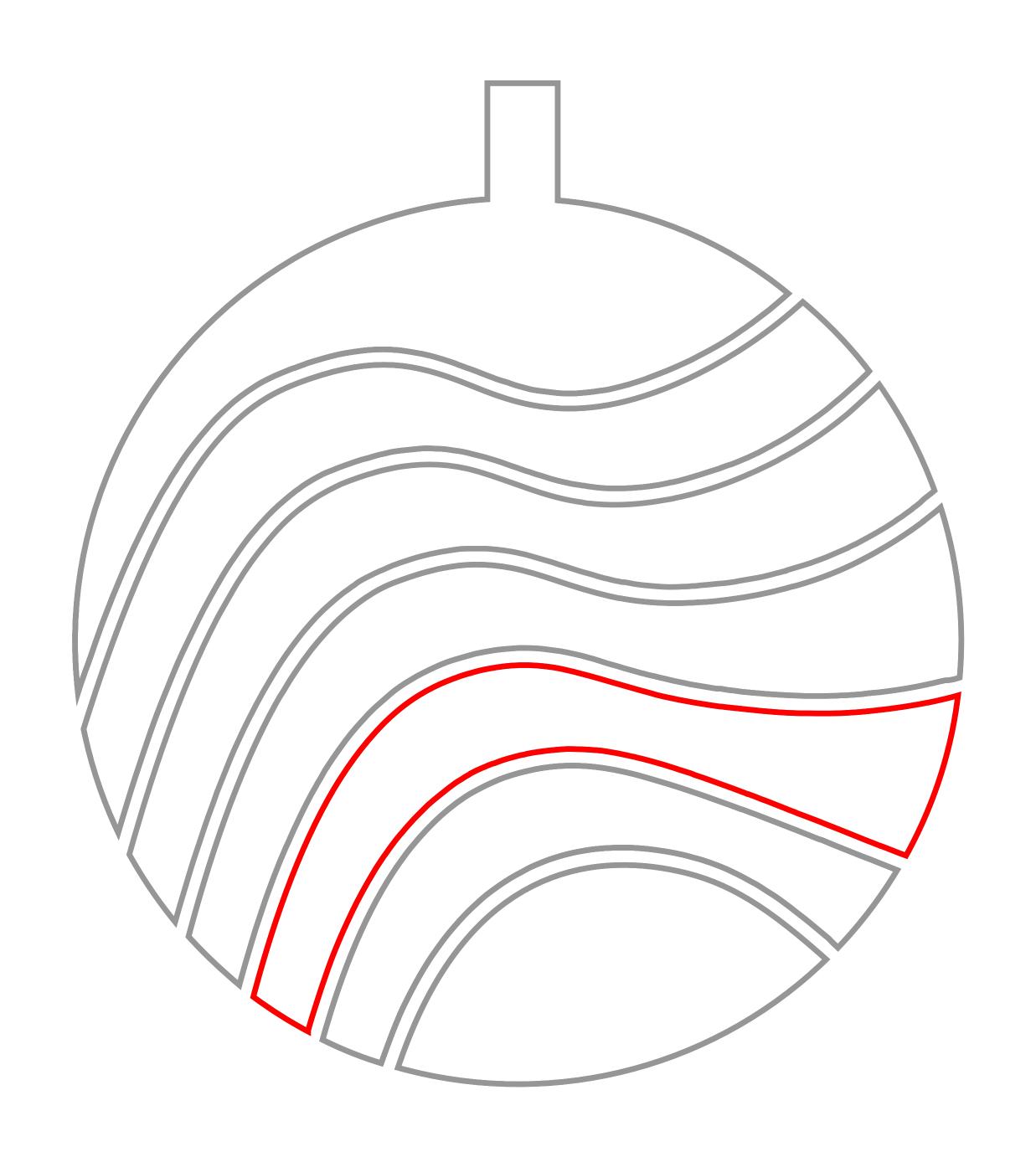
PLACE BASE FACE VOLUMENTE FOR THE PLACE A SHEET OF 0.023MM CELLOPHANE IN THE LASER CUTTER



POWER: 12.5% SPEED: 3%

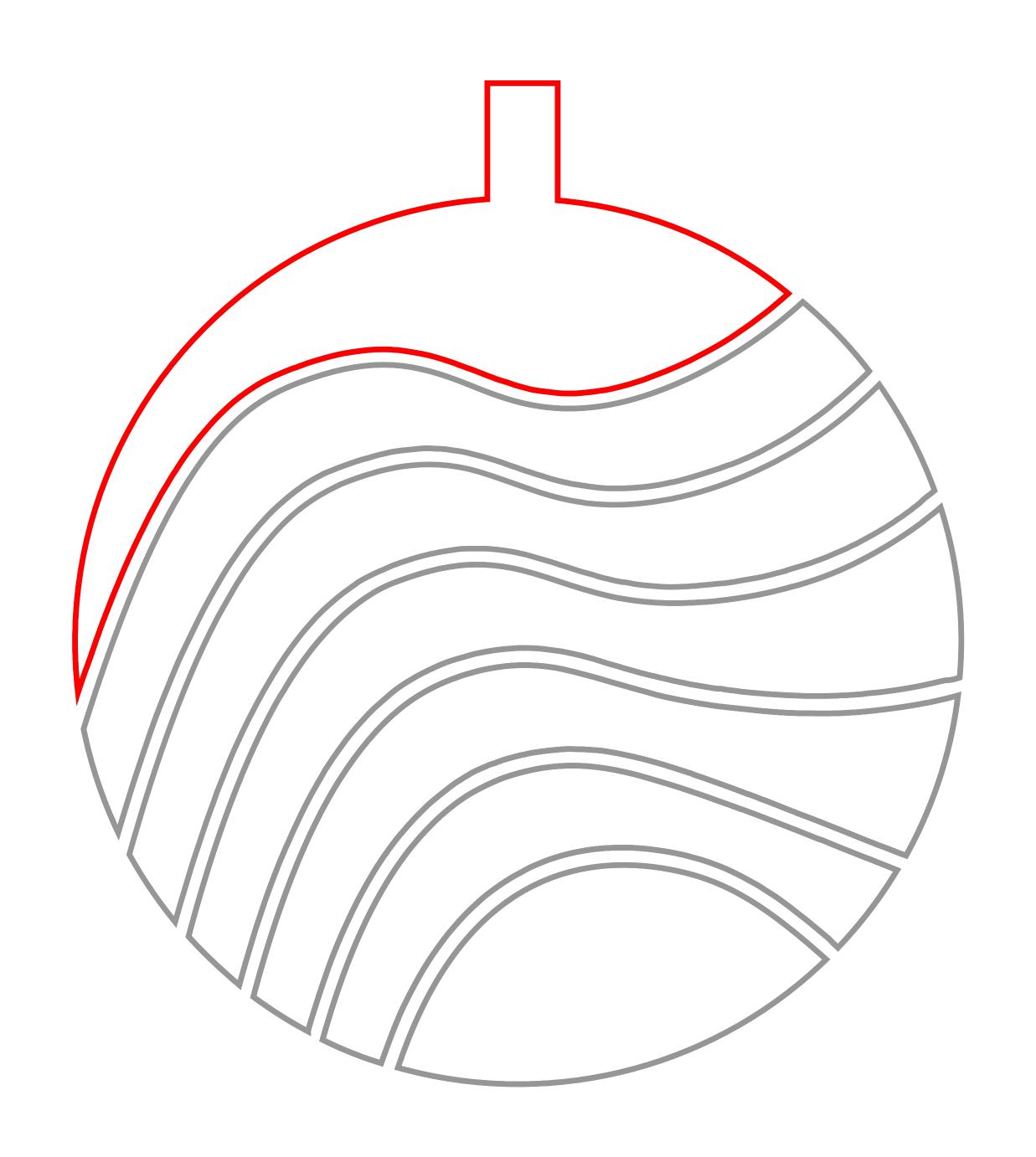
LASER Z: 0.069 MM

CUTTING PASS # 6 PLACE BASE ACRY 230 MSHEEGHTA. PAGMMASER CUTTER PLACE A SHEET OF 0.03MM CELLOPHANE IN THE LASER CUTTER



POWER: 12.5% SPEED: 3% LASER Z: 0.076 MM

CUTTING PASS # 7 PLACE-BAGE3MMRMEIGHSAEQ92MM THE LASER CUTTER PLACE A SHEET OF 0.023MM CELLOPHANE IN THE LASER CUTTER

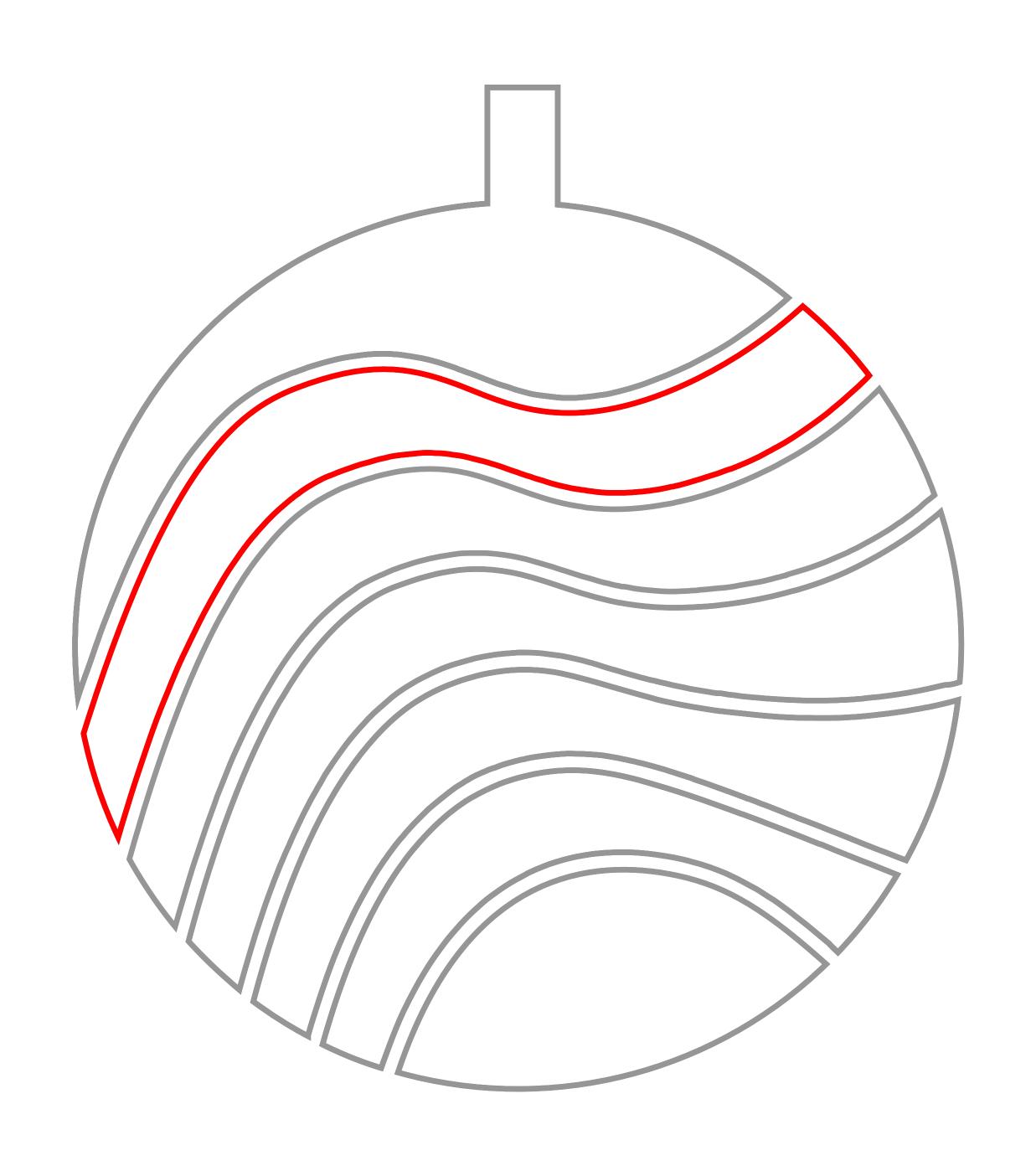


POWER: 12.5% SPEED: 3% LASER Z: 0.092 MM

CUTTING PASS # 8

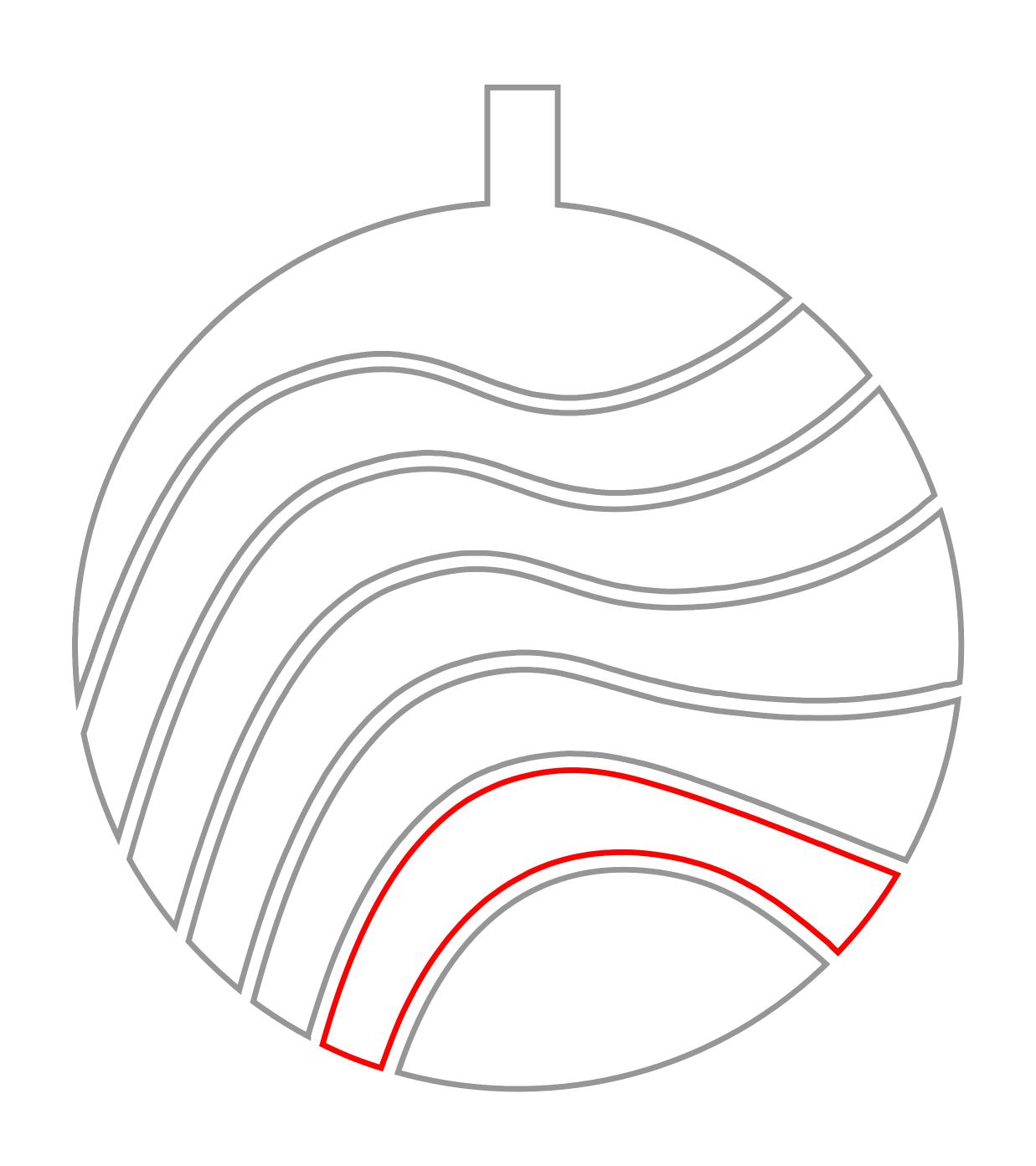
PLACE BASE ARCAMMENTE LASER CUTTER

PLACE A SHEET OF 0.035MM CELLOPHANE IN THE LASER CUTTER



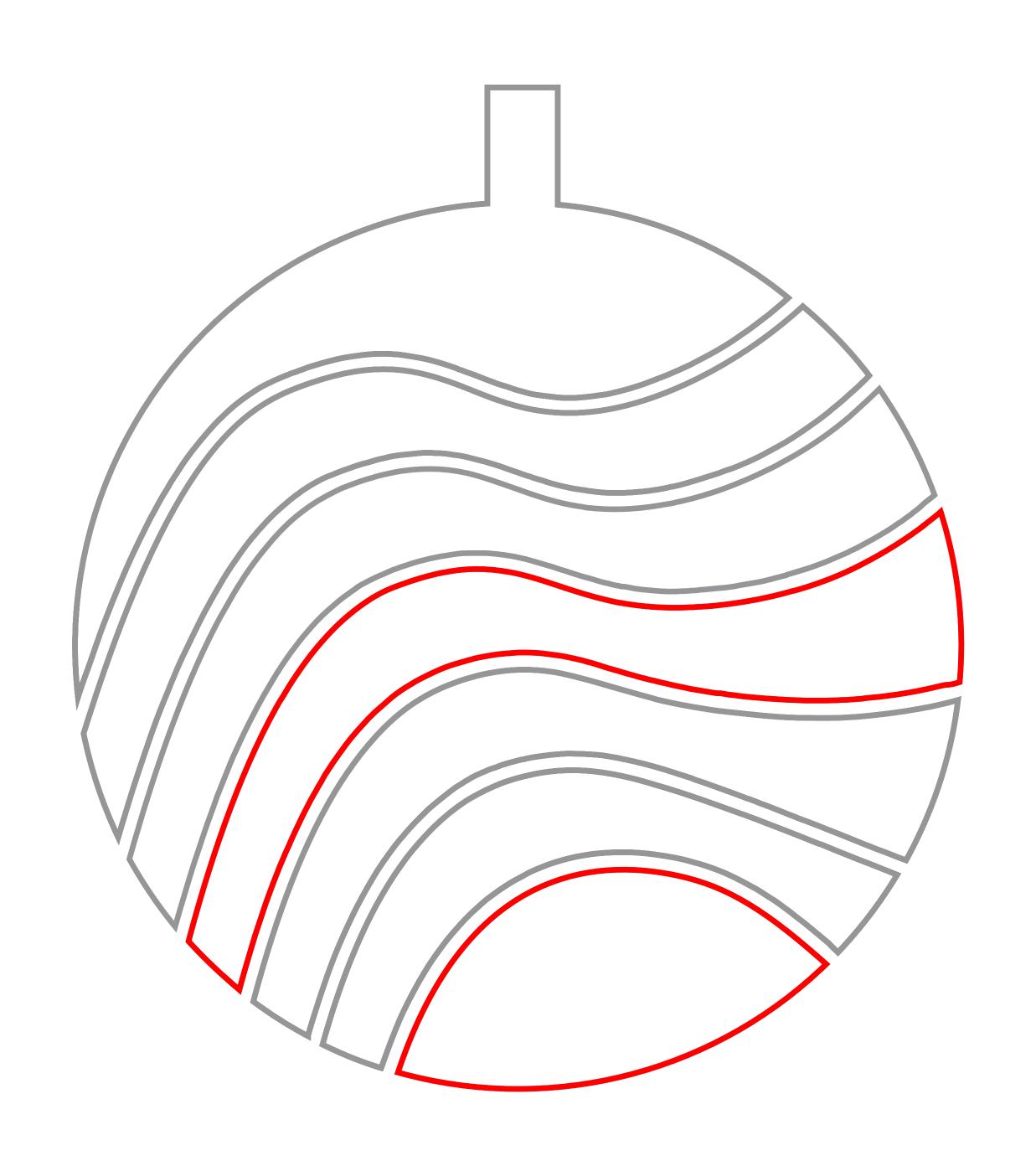
POWER: 12.5% SPEED: 3% LASER Z: 0.093 MM

CUTTING PASS # 9 PLACE BASEO ACOMMETHE SOME EN OF O.OSMM CELLOPHANE IN THE LASER CUTTER PLACE A SHEET OF O.OSMM CELLOPHANE IN THE LASER CUTTER



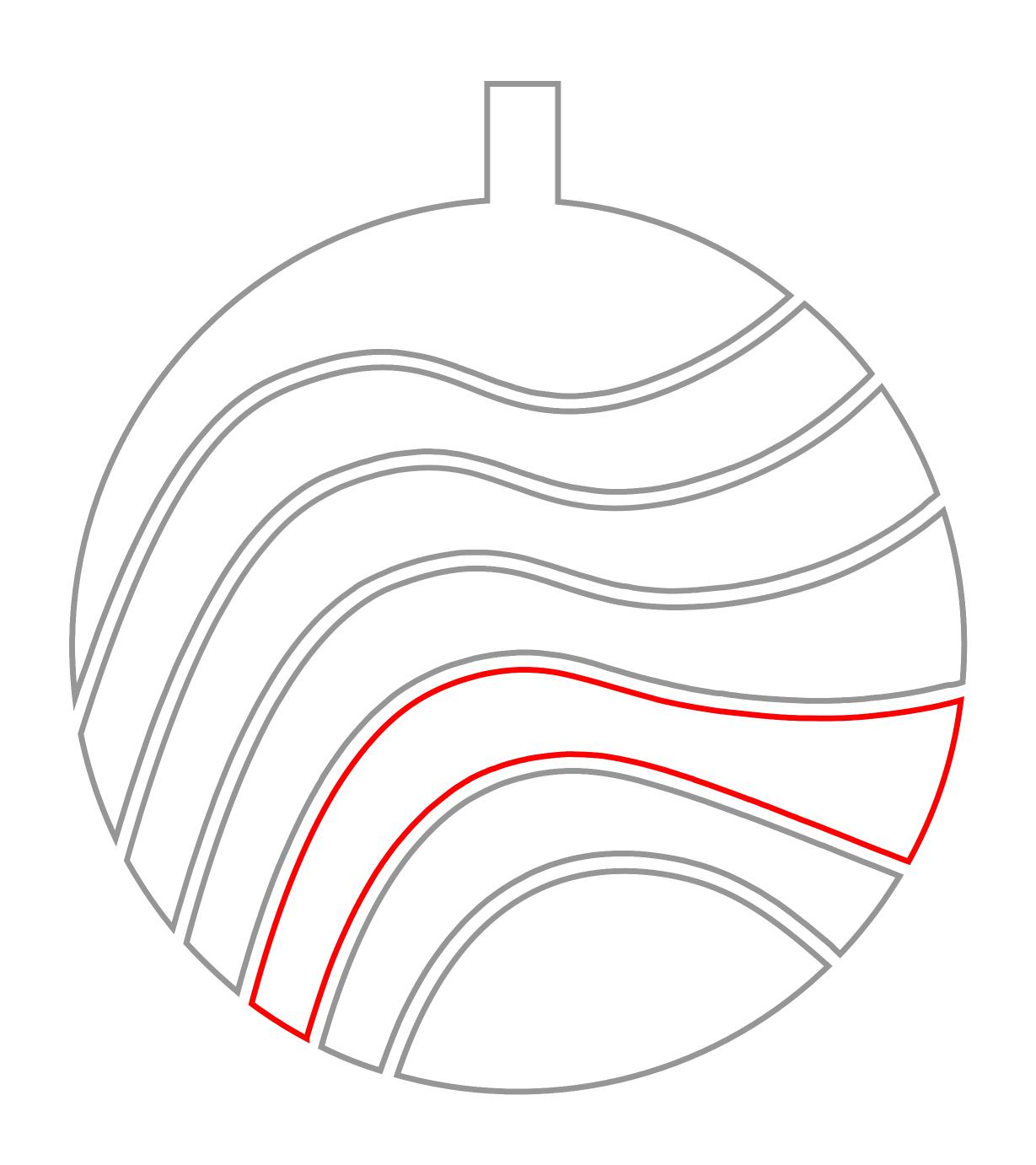
POWER: 12.5% SPEED: 3% LASER Z: 0.099 MM

CUTTING PASS # 10 PLACE BASEO A OR STAND CHEMENTO IN THE LASER CUTTER PLACE A SHEET OF 0.053MM CELLOPHANE IN THE LASER CUTTER



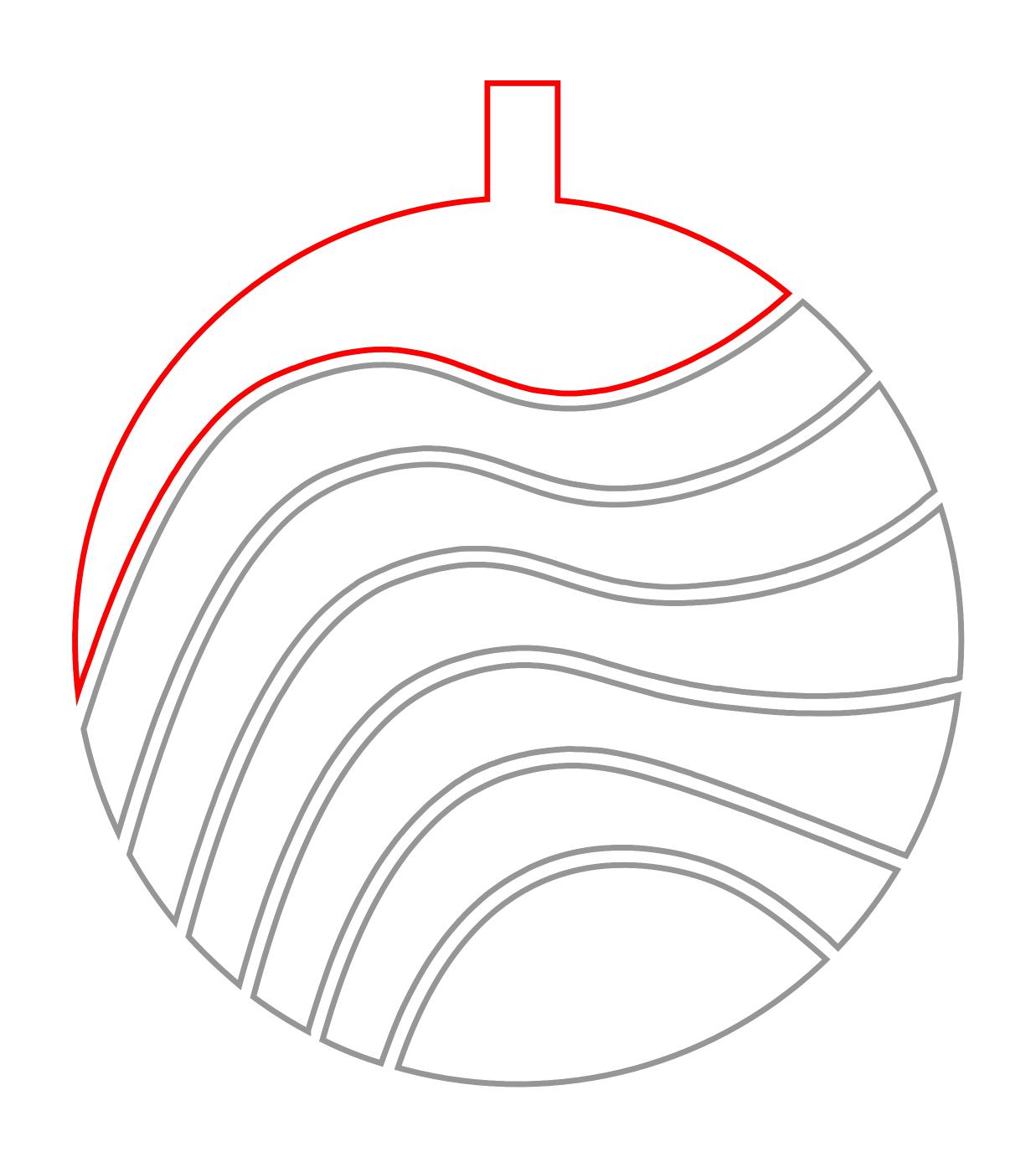
POWER: 12.5% SPEED: 3% LASER Z: 0.099 MM

CUTTING PASS # 11 PLACE BASE 1ACTOY LOIS MINSTHEET GHITNO THE MASER CUTTER PLACE A SHEET OF 0.03MM CELLOPHANE IN THE LASER CUTTER



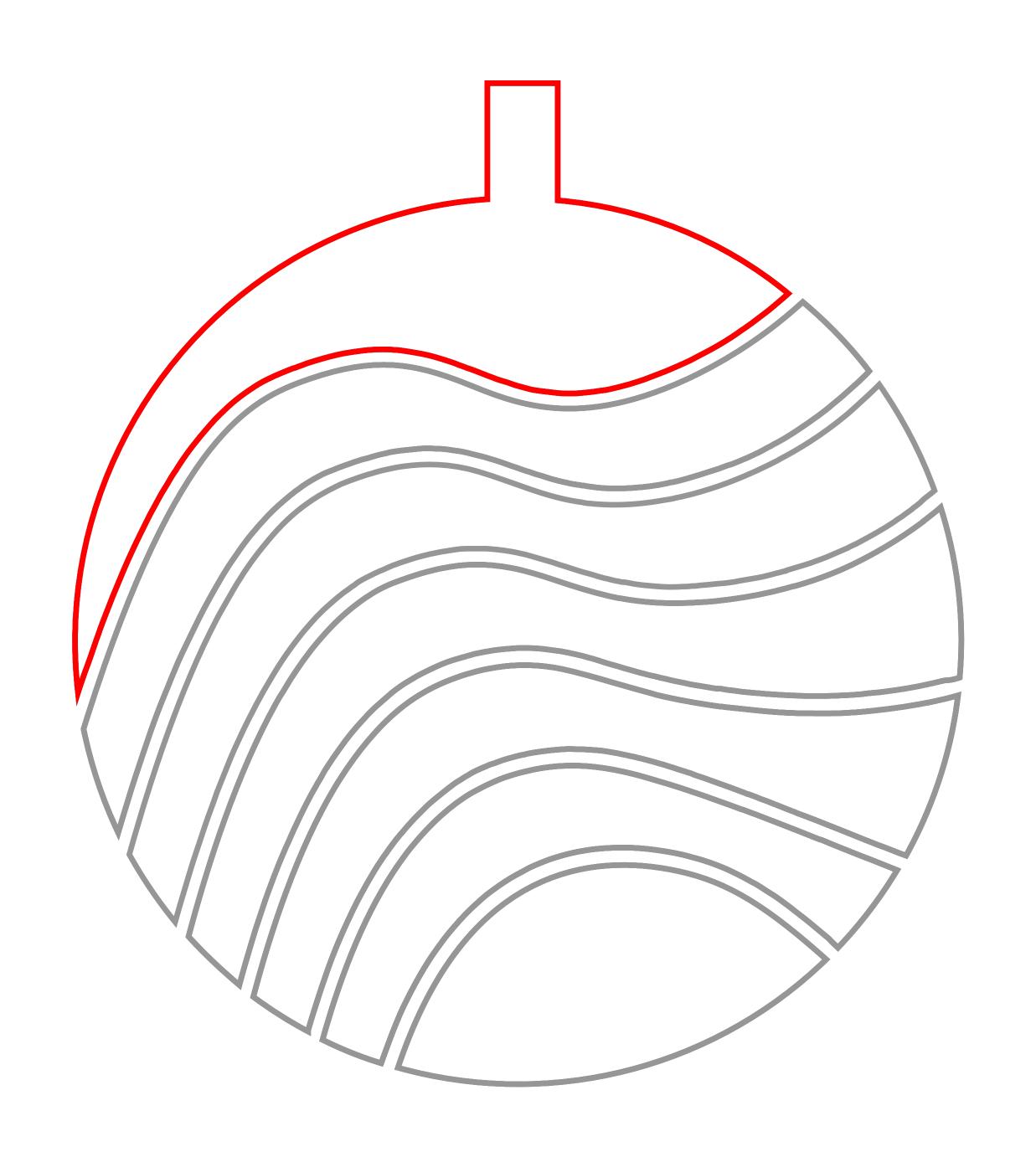
POWER: 12.5% SPEED: 3% LASER Z: 0.106 MM

CUTTING PASS # 12 PLACE BASE 1 ACRY 2 2 2 M M H H E T G M NOT H E 5 M M SER CUTTER PLACE A SHEET OF 0.023 MM CELLOPHANE IN THE LASER CUTTER



POWER: 12.5% SPEED: 3% LASER Z: 0.115 MM

CUTTING PASS # 13 PLACE BASE A CRY 2 2 2 M M H H E T G M NO T H 2 8 M M SER CUTTER PLACE A SHEET OF 0.023 MM CELLOPHANE IN THE LASER CUTTER



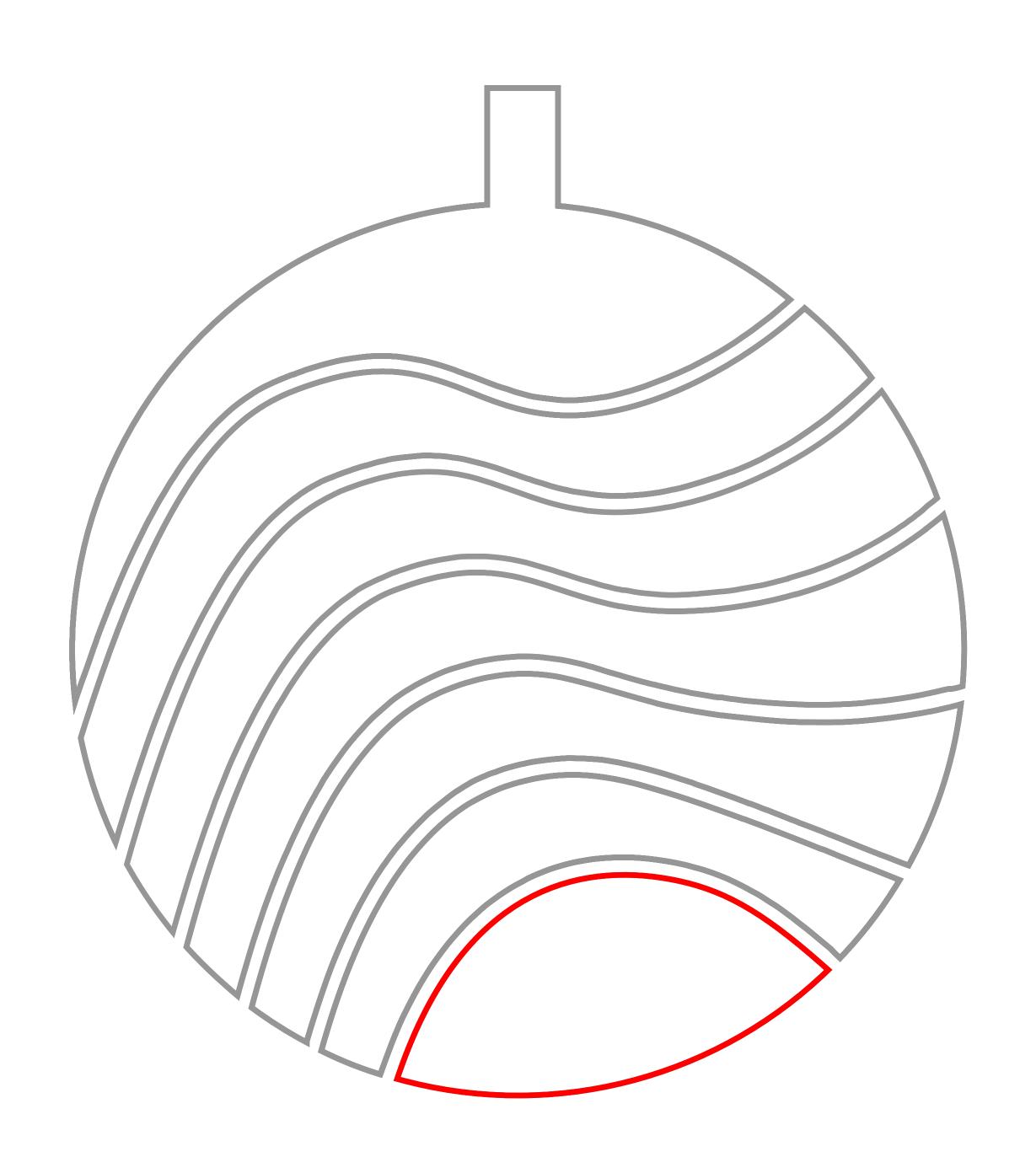
POWER: 12.5% SPEED: 3% LASER Z: 0.138 MM

CUTTING PASS # 14 PLACE BASE SHOWN HEIGHT BE LASER CUTTER PLACE A SHEET OF 0.053MM CELLOPHANE IN THE LASER CUTTER



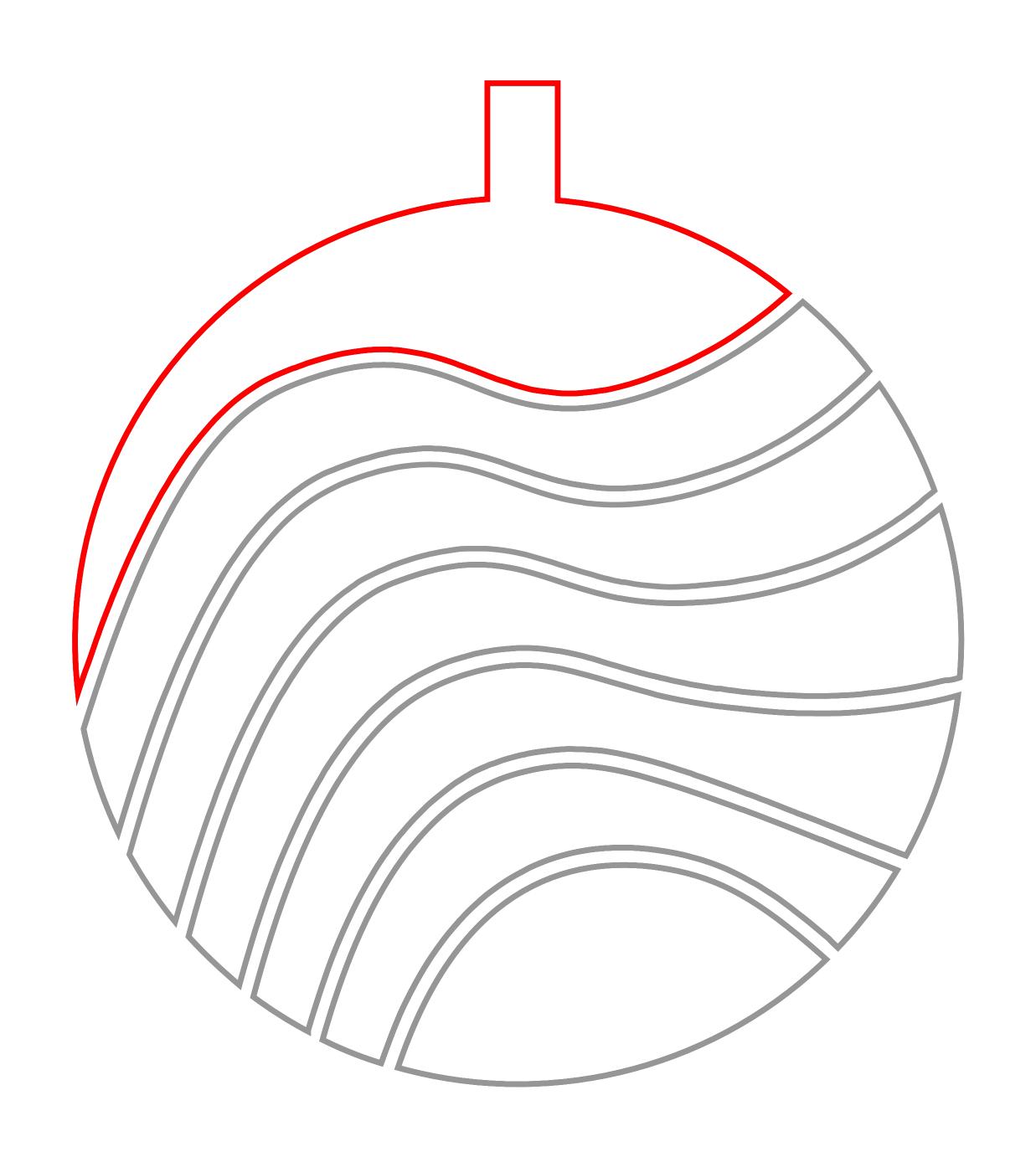
POWER: 12.5% SPEED: 3% LASER Z: 0.146 MM

CUTTING PASS # 15 PLACE BASEOAOROMOCHEMENTOIN52MM LASER CUTTER PLACE A SHEET OF 0.053MM CELLOPHANE IN THE LASER CUTTER



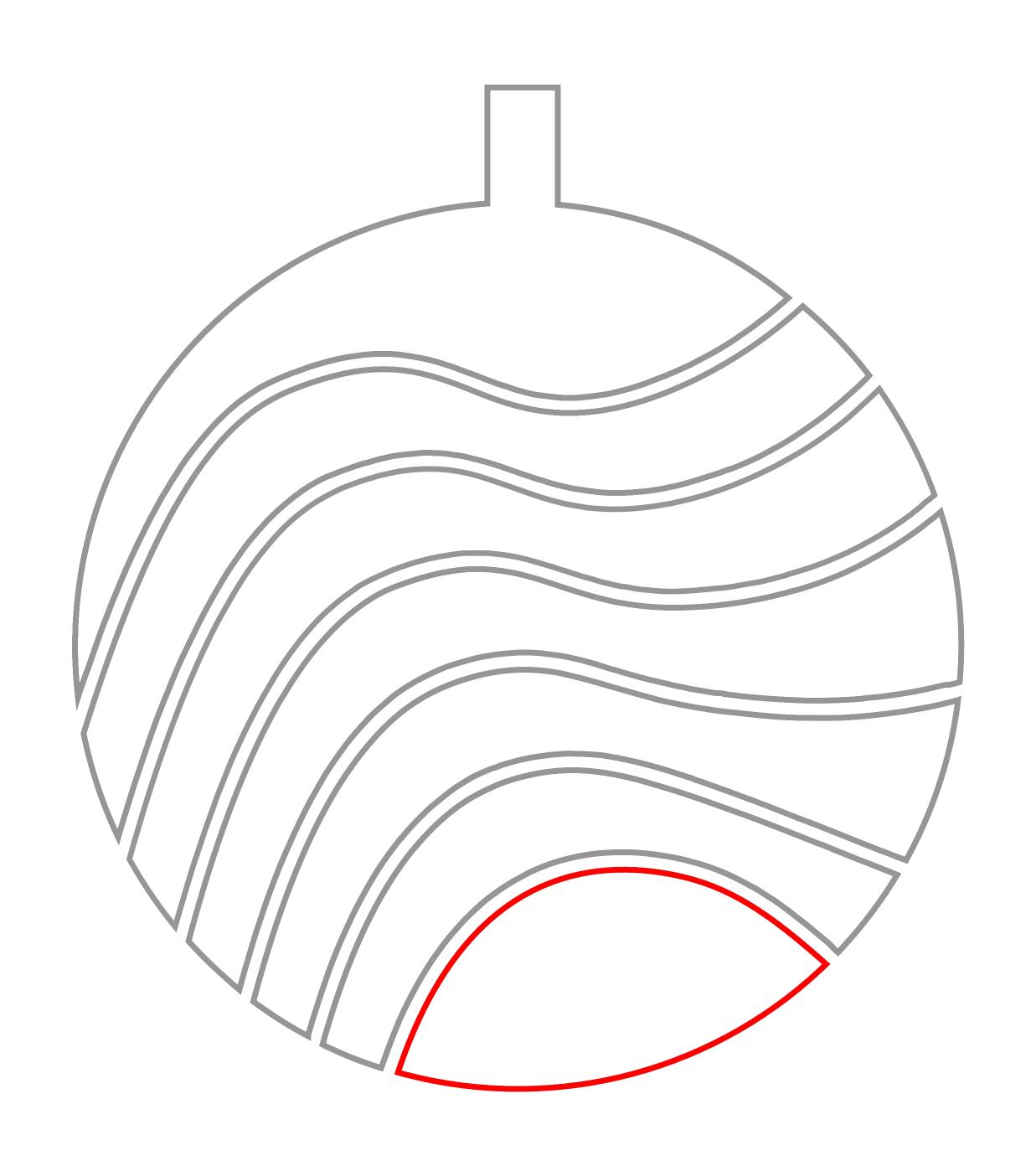
POWER: 12.5% SPEED: 3% LASER Z: 0.152 MM

CUTTING PASS # 16 PLACE BASEOACROMMCHEMETOING THE LASER CUTTER PLACE A SHEET OF 0.023MM CELLOPHANE IN THE LASER CUTTER



POWER: 12.5% SPEED: 3% LASER Z: 0.161 MM

CUTTING PASS # 17 PLACE BASEOAOROMOCHEMENTOIAOTMM LASER CUTTER PLACE A SHEET OF 0.053MM CELLOPHANE IN THE LASER CUTTER



POWER: 12.5% SPEED: 3% LASER Z: 0.205 MM